100% Material Declaration Data Sheet for XCVU11P-FLGF1924

PK1197(v1.0) August 19, 2024

Average Weight : 13.3935 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					**1.680497**	**12.547%**
	Silicon	7440-21-3	100.00	basis	1.680497	
Micro-bump					**0.018627**	**0.139%**
	Copper	7440-50-8	54.80	metal	0.010208	
	Nickel	7440-02-0	22.69	metal	0.004226	
	Tin	7440-31-5	21.87	metal	0.004074	
	Silver	7440-22-4	0.64	metal	0.000120	
Micro-bump underfill					**0.040422**	**0.302%**
	Amorphous silica	trade secret	46.87	Filler	0.018945	
	Amine compound	trade secret	20.84	Glue	0.008422	
	Epoxy resin compound-A	trade secret	15.63	Glue	0.006317	
	Epoxy resin compound-B	trade secret	15.63	Glue	0.006317	
	Epoxy resin compound-C	trade secret	1.04	Glue	0.000421	
Molding compound					**0.087191**	**0.651%**
	Silica filler (SiO2)	trade secret	86.02	Filler	0.075003	
	Epoxy resin	trade secret	8.60	Glue	0.007500	
	Hardener resin	trade secret	5.38	Glue	0.004688	
Interposer die					**0.390132**	**2.913%**
	Silicon	7440-21-3	100.00	basis	0.390132	
C4 Bump					**0.082705**	**0.618%**
	Copper	7440-50-8	70.73	metal	0.058499	
	Tin	7440-31-5	28.53	metal	0.023594	
Solder Paste	Silver	7440-22-4	0.74	metal	0.000612	
					0.058664	**0.438%**
	Tin	7440-31-5	96.50	metal	0.056611	
	Silver	7440-22-4	3.00	metal	0.001760	
	Copper	7440-50-8	0.50	metal	0.000293	
Substrate					**11.035277**	**82.393%**
	Copper	7440-50-8	36.17	metal	3.996678	
	Tin	7440-31-5	0.15	metal	0.017169	
	Core	trade secret	46.17	Glue	5.099481	
	Plugging	trade secret	0.81	Glue	0.089747	
	ABF	trade secret	15.41	Glue	1.701000	
	Solder Mask	trade secret	0.98	Glue	0.108619	
	Nickel	7440-02-0	0.20	metal	0.022571	
	Palladium	7440-05-3	0.02	metal	0.000003	
	Gold	7440-57-5	0.07	metal	0.000009	

Revision History

Date	Version	Description of Revisions
8/19/2024	1.0	Initial AMD Release.

Notice of Disclaimer

AMD regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. AMD subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers (“Contractors”). All data provided hereunder is based on information received from Contractors. AMD has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of AMD products.